

THine®



High Speed Interface Evaluation Kit

THEVA251-SMA-V3 User's Guide

THCS251 Evaluation Kit

THine Electronics, Inc.

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1. Introduction

1.1 Overview

THEVA251-SMA-V3 is an evaluation board with THCS251 installed. THS251 is a transceiver IC that aggregates 35-bit I/O and allows full-duplex bidirectional communication between master and slave. THEVA251-SMA-V3 is a single board that supports both master and slave. The board set as the master and slave can be connected with a coaxial cable via the SMA connector.

If you prepare a conversion board to the desired connector or cable, you can experiment with various transmission lines. SMA connector land is available. Mount SMAJ103-T16 by soldering. The SMA connector and the 48-bit connector for 35bit I / O are not mounted.

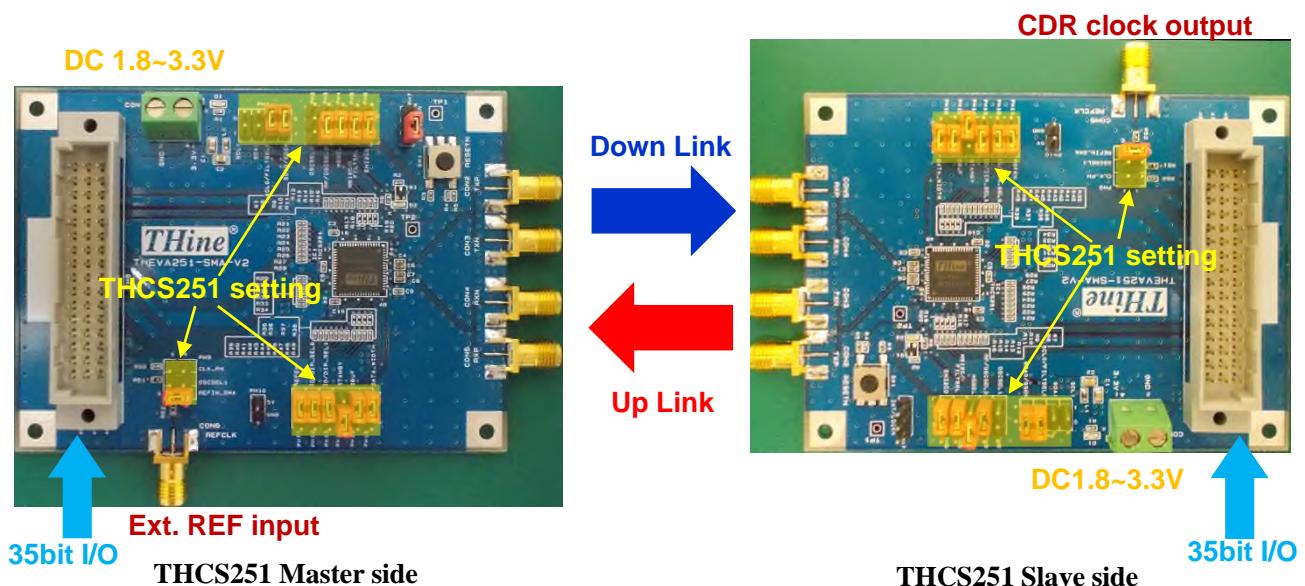


Figure 1 THEVA251-SMA-V3 Master Side / Slave Side top view

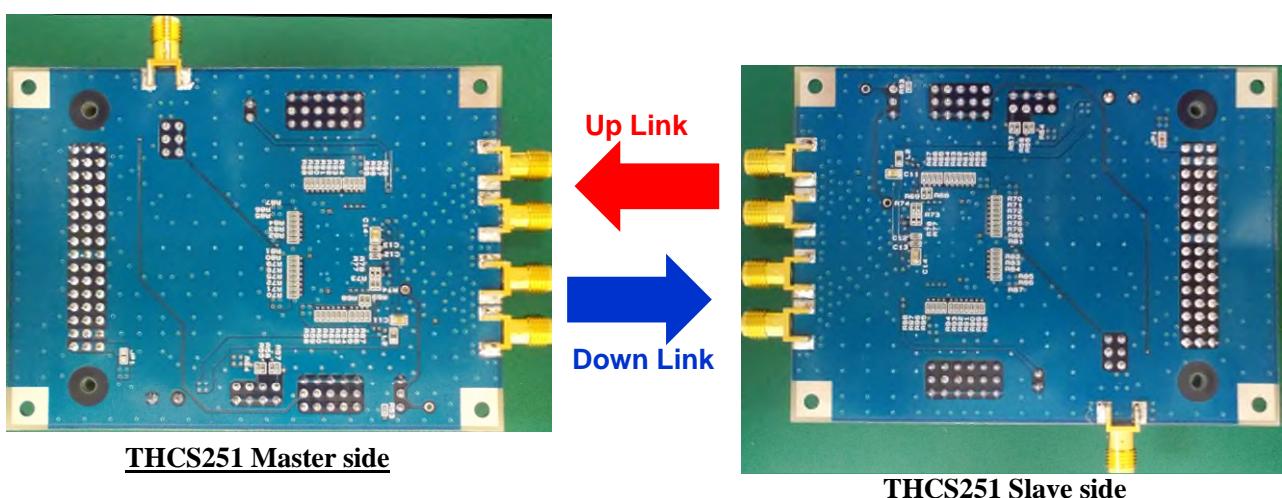


Figure 2 THEVA251-SMA-V3 Master Side / Slave Side bottom view

This document describes the functions and usage of a pair of boards. If you want to check the operation immediately, see 1.3 Quick Start Guidelines. Communication at a data rate of about 600Mbps is established.

* Eight SMAJ103-T16s, DC power supply, four SMA coaxial cables or four SMA connectors, and jumper pins must be prepared.

1.2 Contents of evaluation kit

This evaluation kit includes the contents of Table 1.

| Product | Article | Quantity |
|-----------------|-----------------------|----------|
| THEVA251-SMA-V3 | THEVA251-SMA-V3 Board | 2 |

Table 1 THEVA251-SMA-V3 contents

1.3 Quick start guide

1.3.1 Connect the master and slave boards with jumper pin settings as shown in Figure 3 using SMA coaxial cables.

1.3.2 When DC3.3V is supplied to the power supply terminals of both boards, the LED of D1 lights up. The master board THCS251 internal oscillator starts operating at 20MHz and outputs a downlink signal. When this signal is received by THCS251 of the slave board and the internal circuit is locked, an uplink signal is output. When this signal is received by THCS251 of the master board and the internal circuit is locked, communication between the master and slave is established. When communication is established, THCS251 READY = H and D2 LED lights.

1.3.3. In this state, the built-in oscillator 20MHz operates as the sampling clock, and serialization of 30 times is applied when DATAWIDTH = L. Communication is performed at a speed of 600Mbps for both downlink and uplink.

* Since this is an internal oscillator of the LSI, the sampling clock and transmission rate may vary up to +/- 20%.

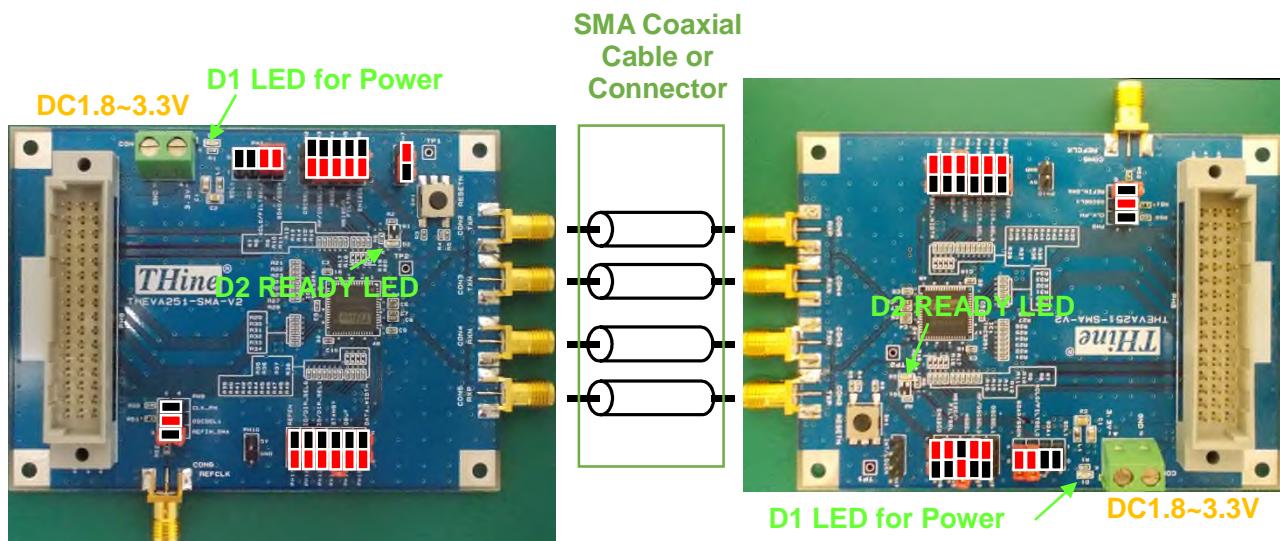


Figure 3 THEVA251-SMA-V3 Quick start pin setting

2. Details about each part of the board

2.1 Power Supply

For THEVA251-SMA-V3, there is a method to supply the desired voltage in the range of 1.7V to 3.6V to the CON1 power terminal block of the master side board and the slave side board. Alternatively, pins 1, 2, and 3 of 48-pin PH8 can be connected to CON1 via JP1 on the bottom of the board, power can be shared from the front and rear circuits via pins 1, 2, and 3 of PH8 is possible.



Figure 4 THEVA251-SMA-V3 Power supply

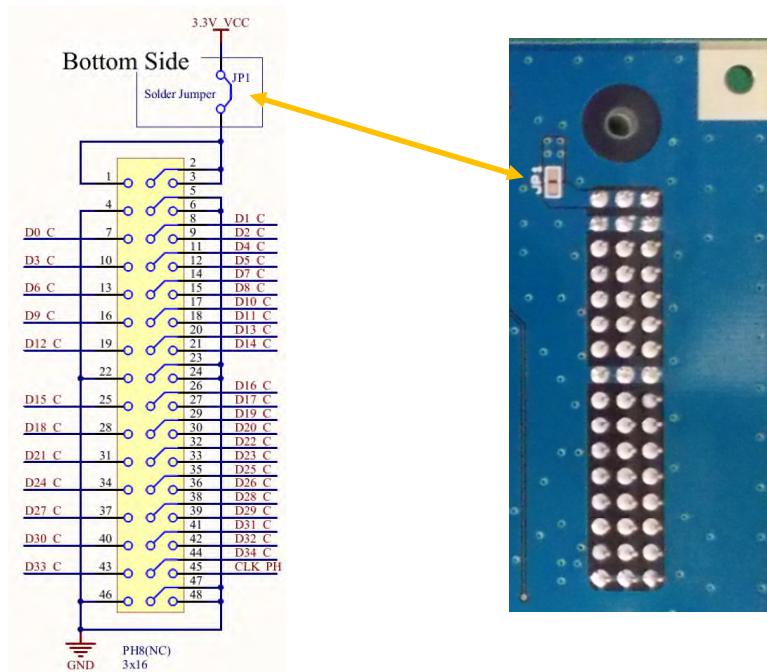
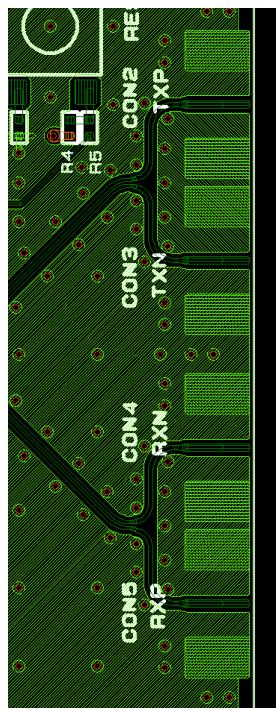


Figure 5 THEVA251-SMA-V3 Power sharing

2.2 Full-duplex high-speed signal connector

THEVA251-SMA-V3 uses SMA connectors for high-speed signal input / output. Prepare SMAJ103-T16 because the board layout is SMAJ103-T16 land pattern design.

**SMA Connector
SMAJ103-T16 Land pattern**



**SMA Connector
SMAJ103-T16 Mounting image**

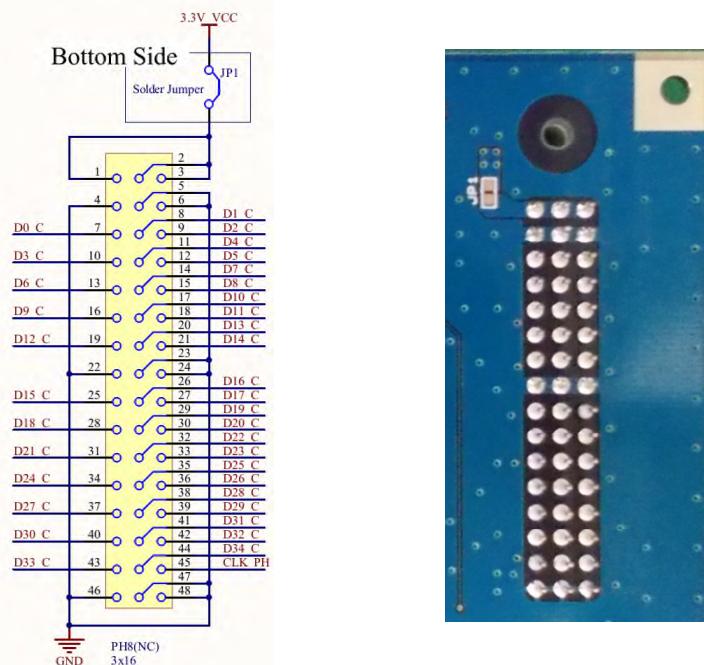


Figure 6 THEVA251-SMA-V3 High Speed CML I/O connector

2.3 Pin header and Connector

* PH8 is not mounted.

PH8 48-pin layout has 35 pins for I/O, 1 pin for external REF input (master) / CDR clock output (slave), 3 pins for power supply sharing, and 10 pins for GND. Connect the I/O circuits on the master side and slave side according to the THCS251 mode setting.



Chip Master Side

| | | | | |
|----|-----------|-----------|-----------|----|
| 1 | VCC | VCC | VCC | 3 |
| 4 | GND | GND | GND | 6 |
| 7 | D0 / D34 | D1 / D33 | D2 / D32 | 9 |
| 10 | D3 / D31 | D4 / D30 | D5 / D29 | 12 |
| 13 | D6 / D28 | D7 / D27 | D8 / D26 | 15 |
| 16 | D9 / D25 | D10 / D24 | D11 / D23 | 18 |
| 19 | D12 / D22 | D13 / D21 | D14 / D20 | 21 |
| 22 | GND | GND | GND | 24 |
| 25 | D15 / D19 | D16 / D18 | D17 / D17 | 27 |
| 28 | D18 / D16 | D19 / D15 | D20 / D14 | 30 |
| 31 | D21 / D13 | D22 / D12 | D23 / D11 | 33 |
| 34 | D24 / D10 | D25 / D9 | D26 / D8 | 36 |
| 37 | D27 / D7 | D28 / D6 | D29 / D5 | 39 |
| 40 | D30 / D4 | D31 / D3 | D32 / D2 | 42 |
| 43 | D33 / D1 | D34 / D0 | CLK | 45 |
| 46 | GND | GND | GND | 48 |

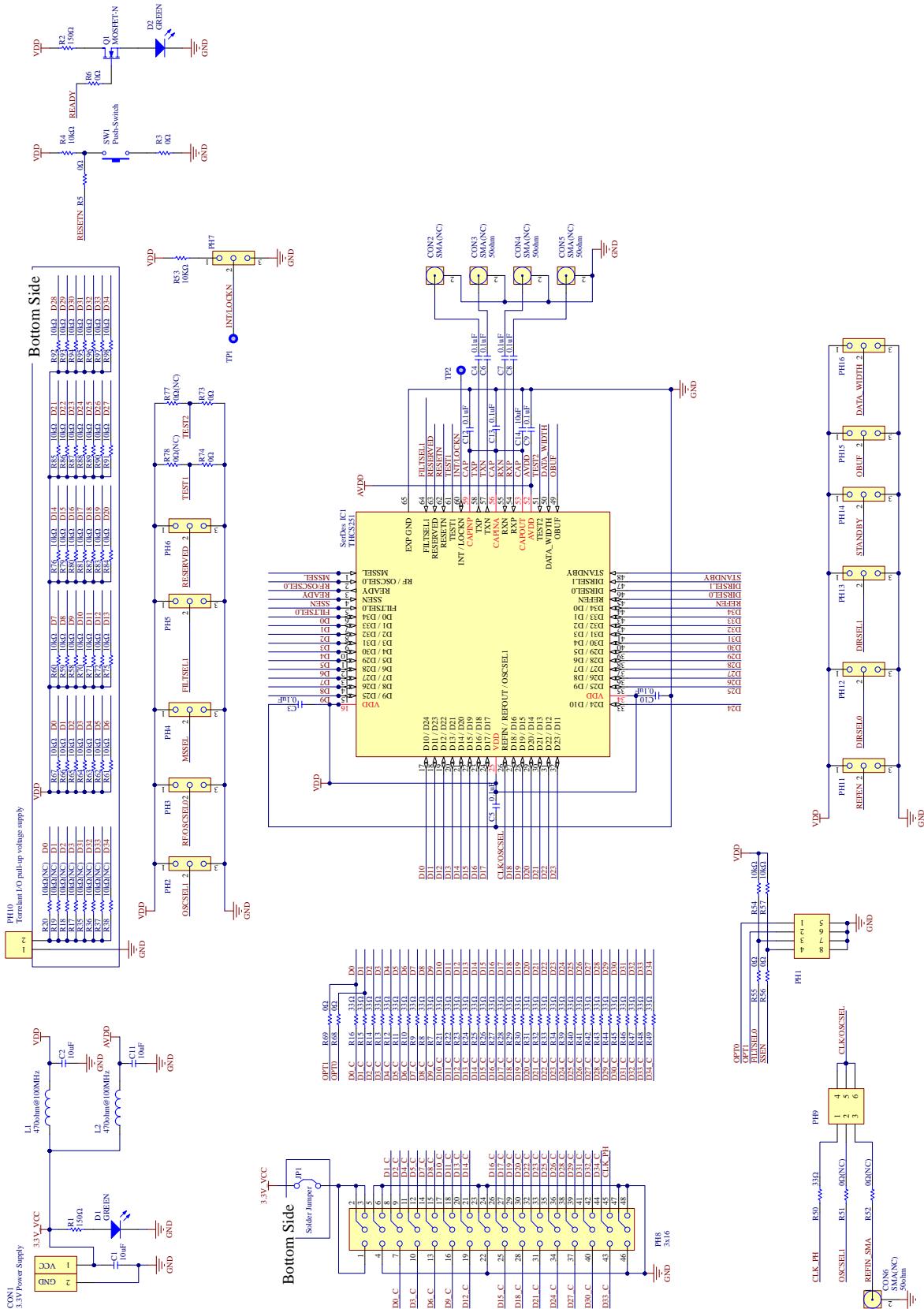
Chip Slave Side

| | | | | |
|----|-----------|-----------|-----------|----|
| 48 | GND | GND | GND | 46 |
| 45 | CLK | D34 / D0 | D33 / D1 | 43 |
| 42 | D32 / D2 | D31 / D3 | D30 / D4 | 40 |
| 39 | D29 / D5 | D28 / D6 | D27 / D7 | 37 |
| 36 | D26 / D8 | D25 / D9 | D24 / D10 | 34 |
| 33 | D23 / D11 | D22 / D12 | D21 / D13 | 31 |
| 30 | D20 / D14 | D19 / D15 | D18 / D16 | 28 |
| 27 | D17 / D17 | D16 / D18 | D15 / D19 | 25 |
| 24 | GND | GND | GND | 22 |
| 21 | D14 / D20 | D13 / D21 | D12 / D22 | 19 |
| 18 | D11 / D23 | D10 / D24 | D9 / D25 | 16 |
| 15 | D8 / D26 | D7 / D27 | D6 / D28 | 13 |
| 12 | D5 / D29 | D4 / D30 | D3 / D31 | 10 |
| 9 | D2 / D32 | D1 / D33 | D0 / D34 | 7 |
| 6 | GND | GND | GND | 4 |
| 3 | VCC | VCC | VCC | 1 |

Figure 7 HEVA251-SMA-V3 Pin header for I/O_PH8

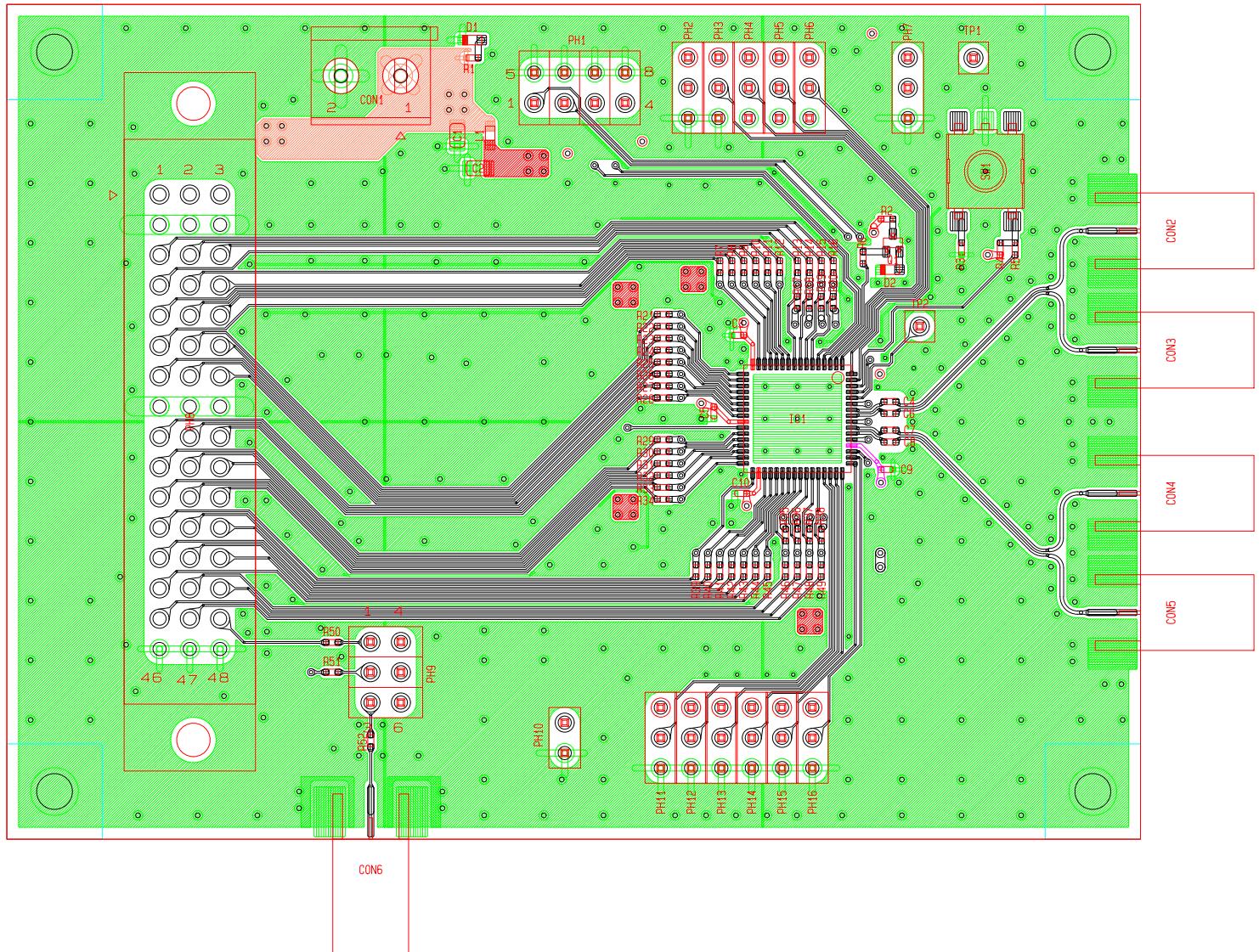
3. Schematic and Layout

3.1 Circuit diagram.

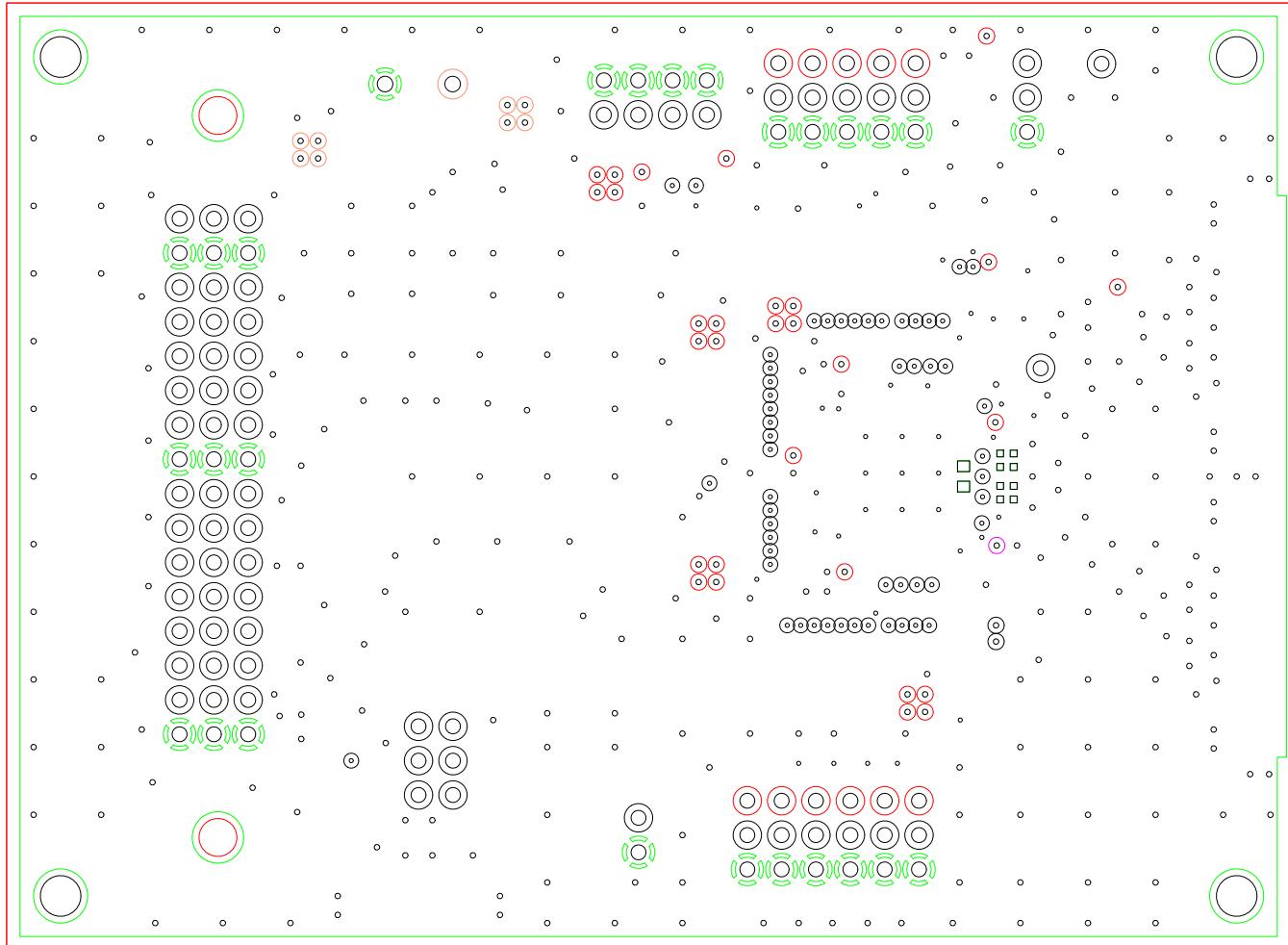


3.2 Layout

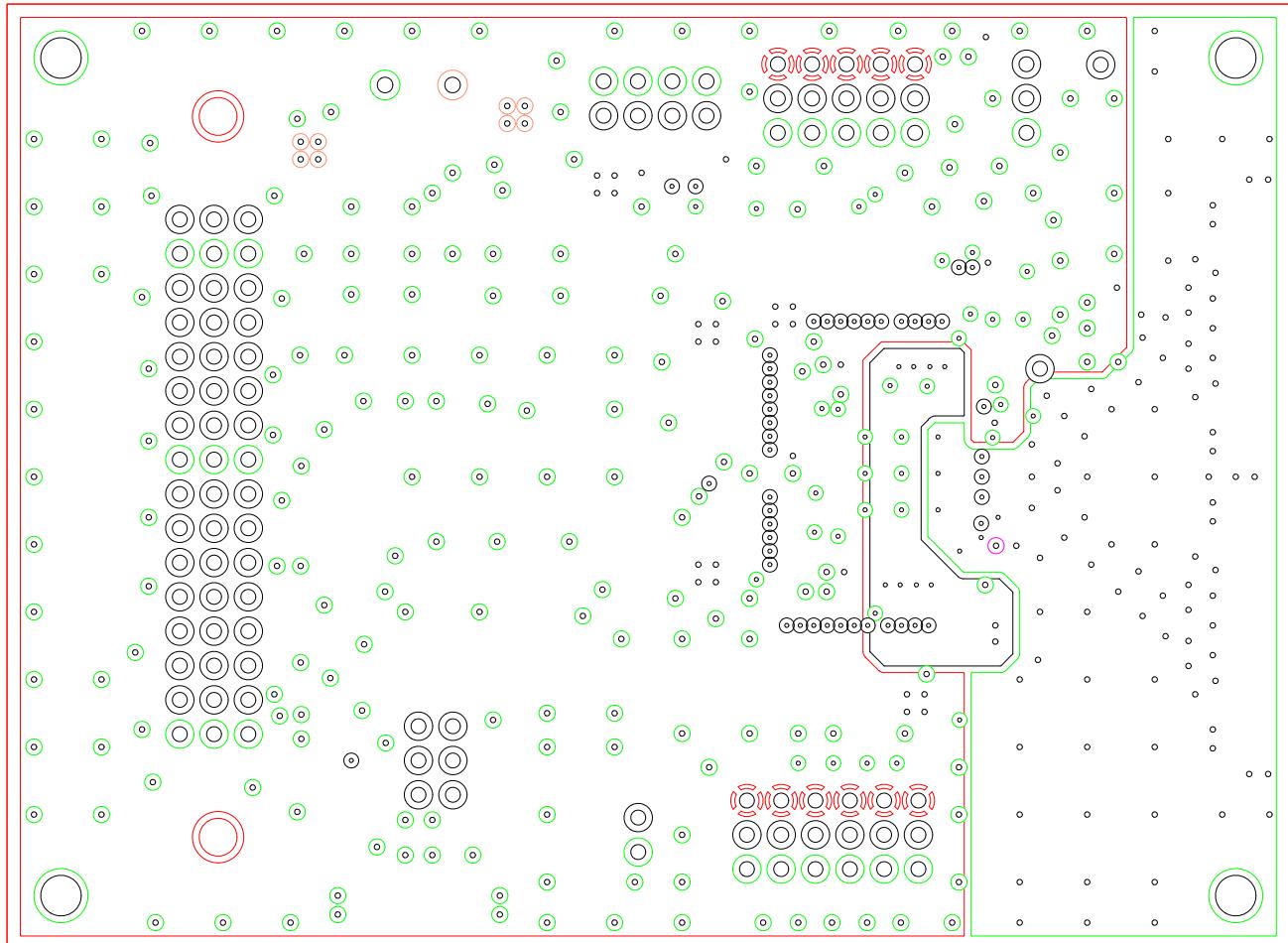
3.2.1 L1(TOP)pattern



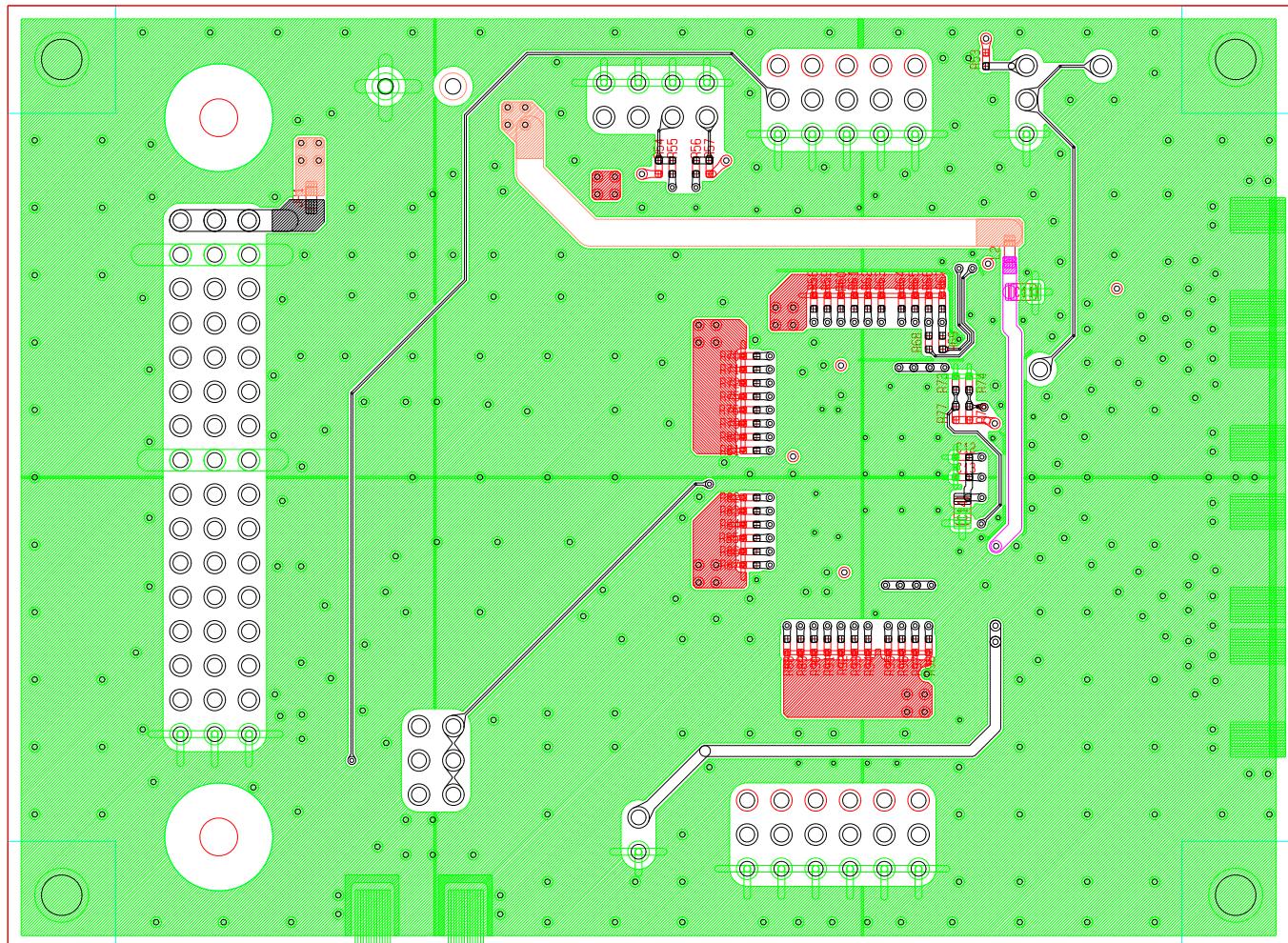
3.2.2 L2 pattern



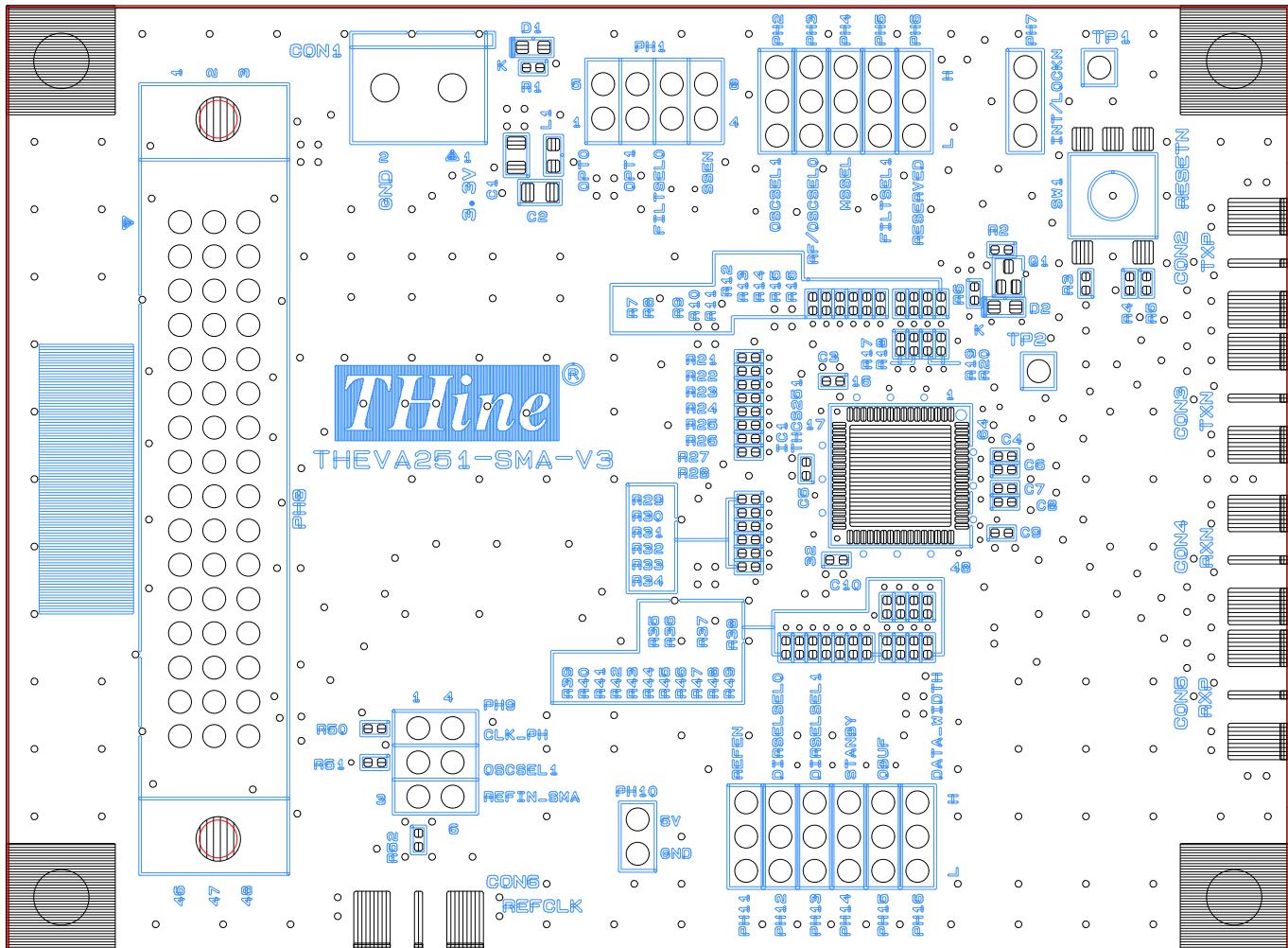
3.2.3 L3 pattern



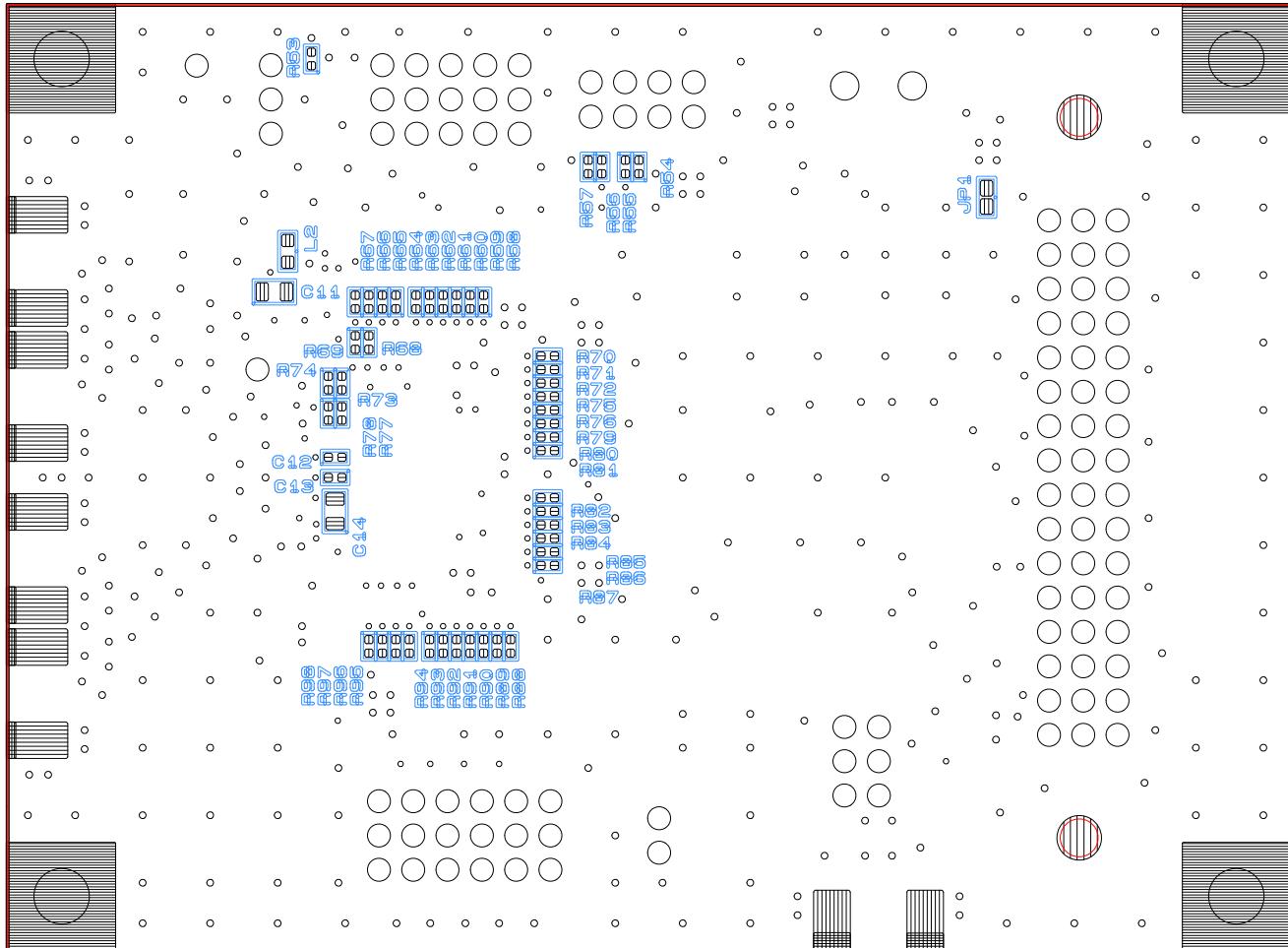
3.2.4 L4 pattern



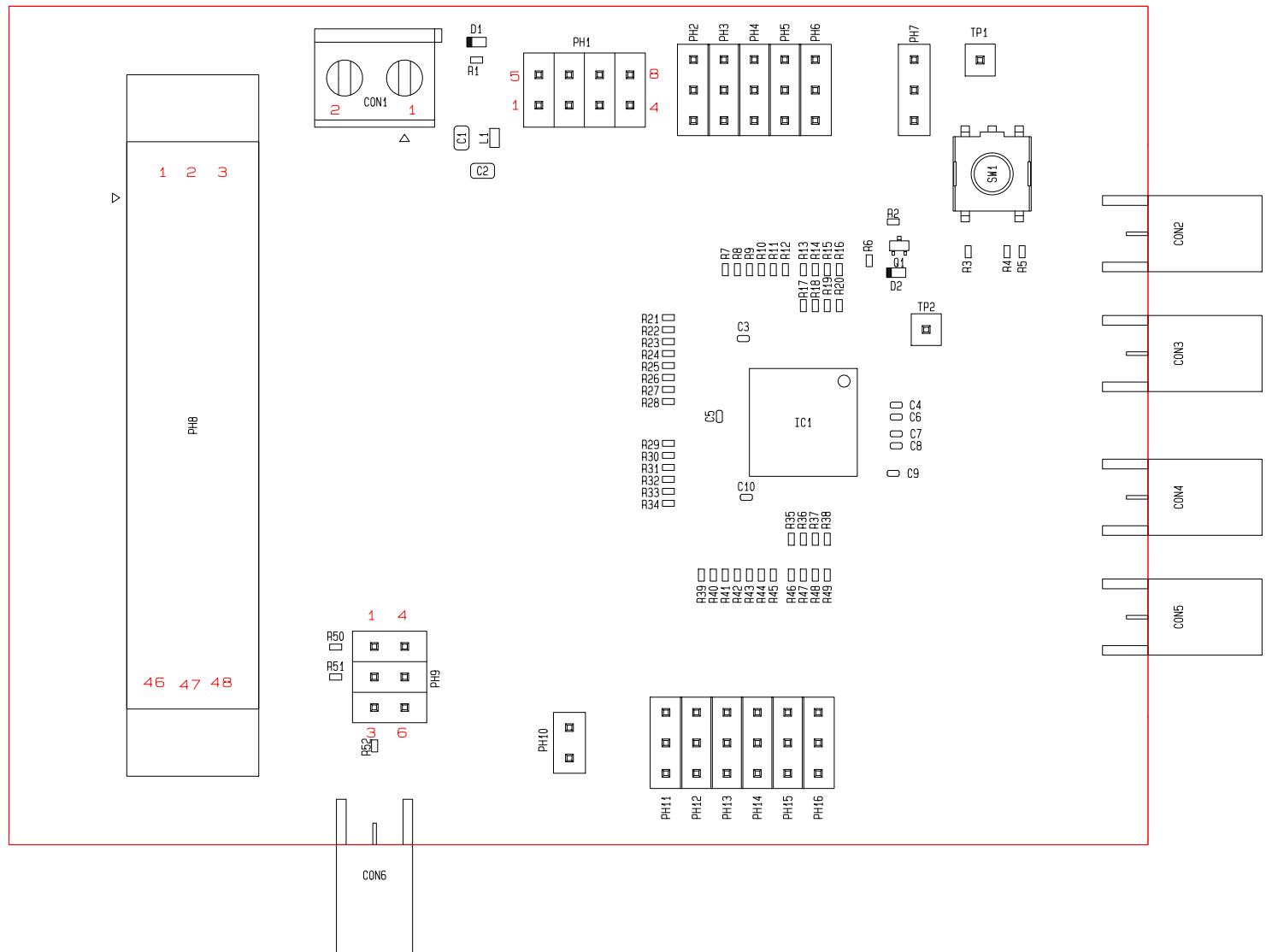
3.2.5 TOP side silk



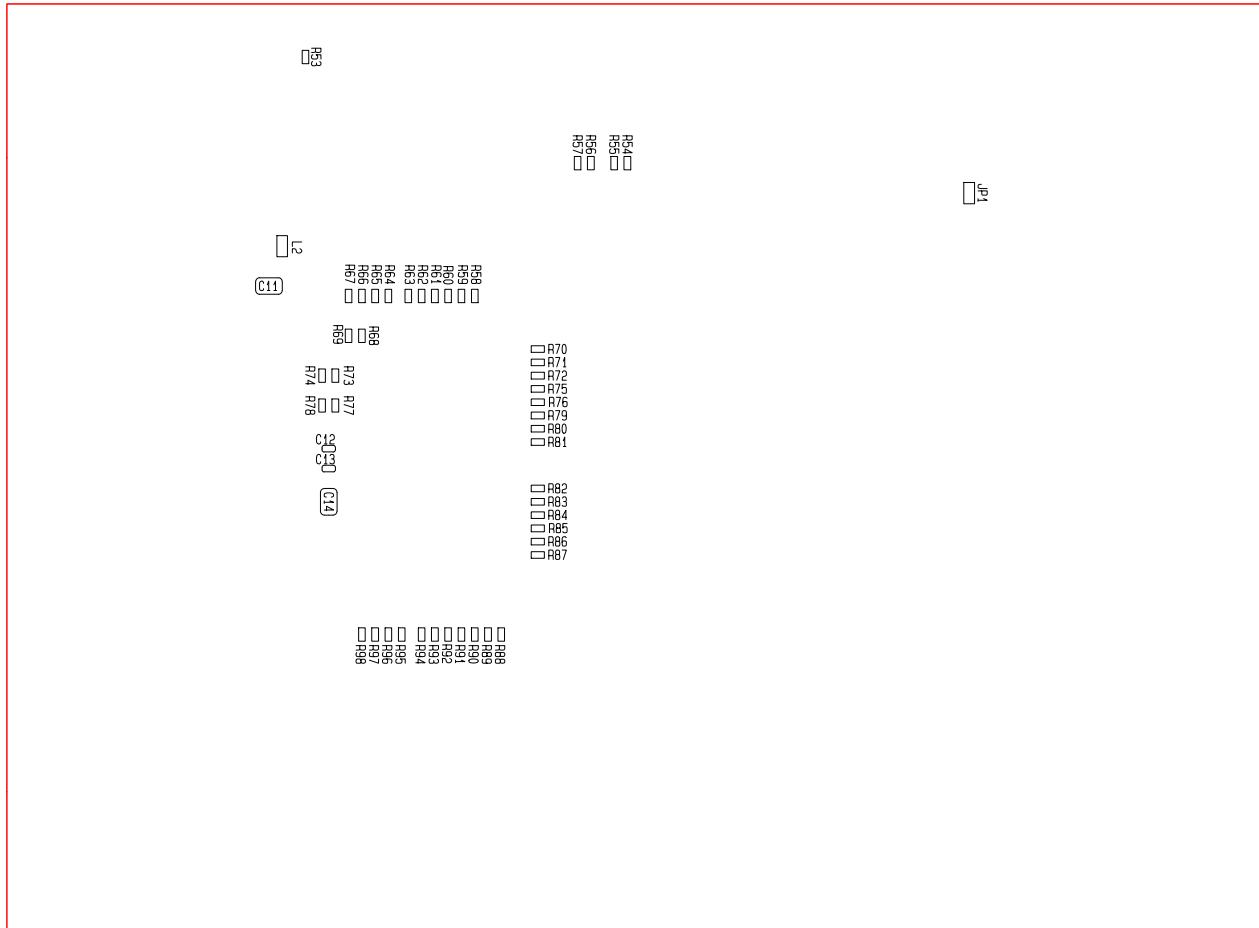
3.2.6 BOTTOM side silk



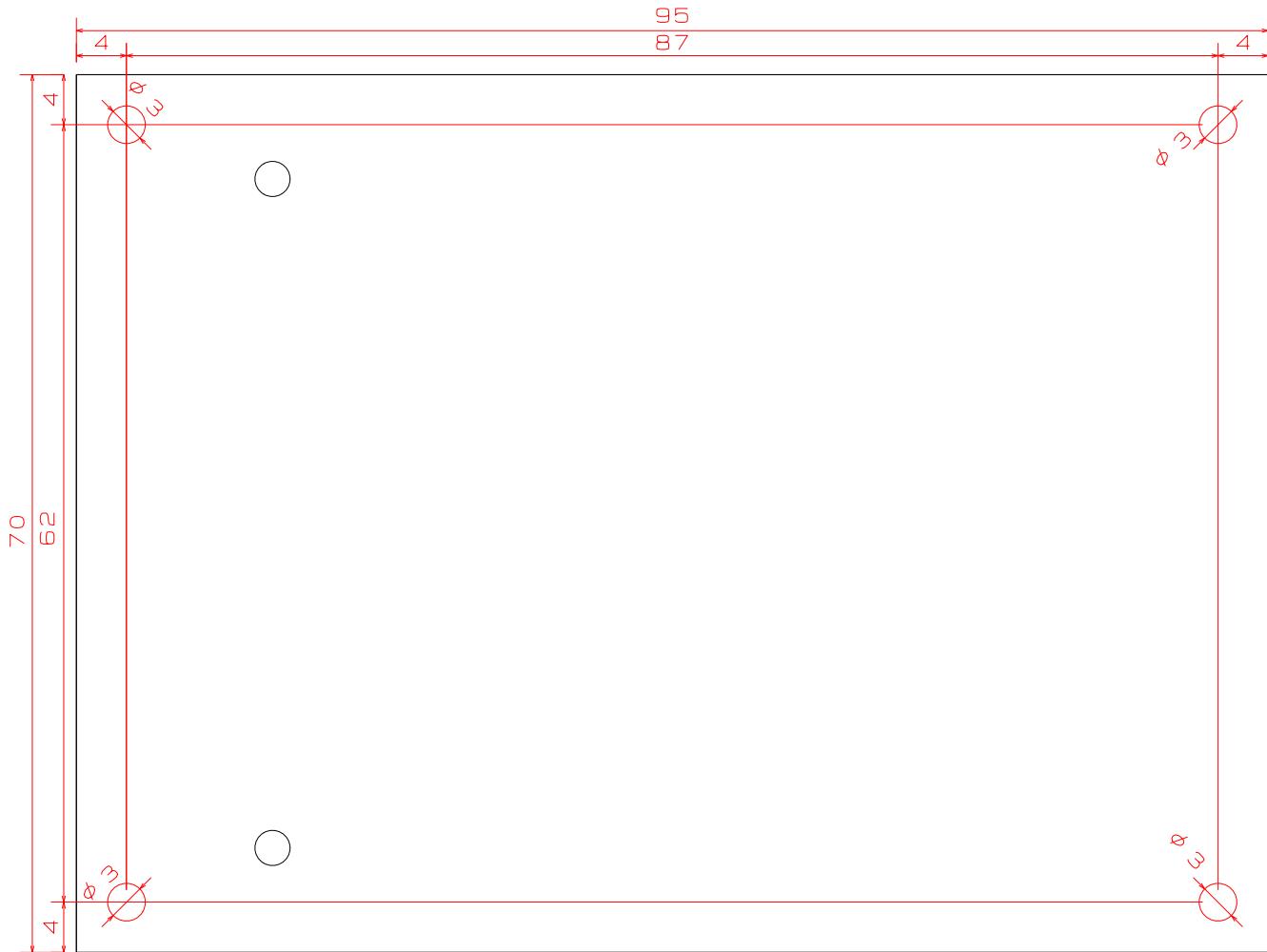
3.2.7 TOP side implementation



3.2.8 BOTTOM side implementation



3.2.9 Dimensions



4. BOM

| Designator | Description | Value | Quantity | P/N |
|--|----------------|---------------|----------|-----------------------|
| C1, C2, C11, C14 | Cap. 2012 | 10uF | 4 | GRM21BB31C106KE15L |
| C3, C4, C5, C6, C7, C8, C9, C10, C12, C13 | Cap. 1005 | 0.1uF | 10 | GRM155B31E104KA87D |
| CON1 | Terminal_Block | 2pin | 1 | 282836-2 |
| CON2, CON3, CON4, CON5, CON6 | SMA(NC) | 50ohm | 5 | SMA103-T16 |
| D1, D2 | LED | GREEN | 2 | SML-D12P8WT86 |
| IC1 | SerDes | Max. 4Gbps | 1 | THCS251 |
| JP1 | Jumper(NC) | Solder Jumper | 1 | |
| L1, L2 | Coil. 1608 | 470ohm@100MHz | 2 | MPZ1608B471ATA00 |
| PH1 | Header 8 | 2x4 | 1 | TCHM23-70-008S-803R |
| PH2, PH3, PH4, PH5, PH6, PH11, PH12, PH13, PH14, PH15, PH16 | Header 3 | 1x3 | 11 | TCHM13-70-003S-803R |
| PH7 | Header 3 | 1x3 | 1 | TCHM13-70-003S-803R |
| PH8 | Header 48(NC) | 3x16 | 1 | PCN10-48P-2.54DSA(72) |
| PH9 | Header 6 | 2x3 | 1 | TCHM23-70-006S-803R |
| PH10 | Header 2 | 1x2 | 1 | TCHM13-70-002S-803R |
| Q1 | MOSFET | N-ch | 1 | SSM3K16FS |
| R1, R2 | Res. 1005 | 150Ω | 2 | RK73H1ETTP1500F |
| R3, R5, R6, R51, R52, R55, R56, R68, R69, R73, R74 | Res. 1005 | 0Ω | 11 | RK73Z1ETTP0 |
| R4, R53, R54, R57, R58, R59, R60, R61, R62, R63, R64, R65, R66, R67, R70, R71, R72, R75, R76, R79, R80, R81, R82, R83, R84, R85, R86, R87, R88, R89, R90, R91, R92, R93, R94, R95, R96, R97, R98 | Res. 1005 | 10kΩ | 39 | RK73H1ETTP1002F |
| R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R21, R22, R23, R24, R25, R26, R27, R28, R29, R30, R31, R32, R33, R34, R39, R40, R41, R42, R43, R44, R45, R46, R47, R48, R49, R50 | Res. 1005 | 33Ω | 36 | RK73H1ETTP33R0F |
| R17, R18, R19, R20, R35, R36, R37, R38 | Res. 1005(NC) | 10kΩ (NC) | 8 | RK73H1ETTP1002F |
| R77, R78 | Res. 1005(NC) | 0Ω (NC) | 2 | RK73Z1ETTP0 |
| SW1 | SW | Top Push | 1 | SKHMQKE010 |
| TP1, TP2 | Test Point(NC) | Through hole | 2 | |

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